### SCHEMATIC CONTENTS

<table>
<thead>
<tr>
<th>REV</th>
<th>DESCRIPTION</th>
<th>DATE</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>First Released Schematic</td>
<td>12/14/12</td>
</tr>
<tr>
<td>B</td>
<td>Second Released Schematic</td>
<td>6/5/2013</td>
</tr>
</tbody>
</table>

1. RESISTANCE VALUES IN OHMS.
2. CAPACITANCE VALUES IN MICROFARADS.
3. REFERENCE DESIGNATORS USED:
4. ALL 0.1 uF AND 0.01uF CAPACITORS ARE DECOUPLING CAPS UNLESS OTHERWISE NOTED. THEY ARE SHOWN ON THE PAGE WITH THE INTEGRATED CIRCUITS THEY SHOULD BE PLACED NEAR.
5. OBSERVE THE LAYOUT NOTES IN SCHEMATIC.

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5. OBSERVE THE LAYOUT NOTES IN SCHEMATIC.
Title: LOW NOISE AMPLIFIER SECTION

Page Contents: SMA order should be AM/FM1, DAB1, DAB2, AM/FM2, AM/FM3, DAB3, DAB4, and AM/FM4

0.4 inch center to center
SMA order should be AM/FM1, DAB1, DAB2, AM/FM2, AM/FM3, DAB3, DAB4, and AM/FM4
0.4 inch center to center

Load R80= CAP 33pF and C68=33pF for active antenna application.
SMA order should be AM/FM1, DAB1, DAB2, AM/FM2, AM/FM3, DAB3, DAB4, and AM/FM4 0.4 inch center to center

50 ohm xmission line

Shield part # MCH-000119 rev A0

Shield # MXS-ISO119 rev A0
SMA order should be AM/FM1, DAB1, DAB2, AM/FM2, AM/FM3, DAB3, DAB4, and AM/FM4 0.4 inch center to center

50 ohm transmission line

Load R80= CAP 33pF and C68=33pF for active antenna application.

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Title: JAMR 3 APPLICATION BOARD
Page Contents: RADIO Tuner #3
Size: B
DWG NO: 517182-0001
Revision: A
Date: Tuesday, January 12, 2016
Sheet: 11 of 40
SMA order should be AM/FM1, DAB1, DAB2, AM/FM2, AM/FM3, DAB3, DAB4, and AM/FM4 0.4 inch center to center.
3.3 VOLTS AT 1 AMPS

U13
TPS75233QPWP

GND_HS.1
NC.2
NC.19
NC.18
NC.17
NC.16
NC.15
NC.14
SENSE
OUT.1
OUT.2
GND_HS.2
GND_HS.3

3V3_LINEAR1

C363 0.01uF
C354 0.1uF

TP34

C365 33uF

L91
BLM41P750SPT

C349 10uF
C352 0.1uF

TP32
TP24

C354 0.1uF

C337 3300pF

C349 10uF

C352 0.1uF

JAMR 3 APPLICATION BOARD
RADIO POWER

Texas Instruments

Title:
JAMR 3 APPLICATION BOARD
Page Contents:
RADIO POWER

Size:
DWG NO:
517183-0001
Revision:

Date:
Tuesday, January 12, 2016
Sheet:
13 of 40
THESE INDUCTORS STRADDLE TUNER GAP

3.3 VOLTS AT 1 AMPS

3V3_Maxwell_T1T2

DC_3V8

C347 2.2uF

C366 3.3uF

C350 10uF

C353 0.1uF

C364 0.31uF

C355 0.1uF

TP21

TP23

C350 10uF

C353 0.1uF

TP31

TP33

L90

TPS75233QPWP

U12

GND_HS.1 GND_HS.4

GND_HS.2 GND_HS.3

TP23

3V3 LINEART1 T2

3V3_Maxwell_T1T2

3V3_Maxwell_T1T2

TPS75233QPWP

U12
Status Lock and Error Free Receiver uses pins 2 and 4.
J2 to iPod device via USB port
VOUT = 0.8 * (1 + (R_TOP/R_BOTTOM))

1.1 VOLTS AT 0.2 AMPS
3.3 sq in AGND, min thermal pad

3.8 Volts at 2 AMPS
3.3 Volts at 1AMPS  
Fsw=1910KHz

These diodes drop the input supply so that the TPS54362 can operate at Fsw>1800KHz. Can be replaced with a 2512 resistor.

The 3.3V Regulator
The image contains a schematic diagram related to JAMR 3 Application Board System Reset Logic. The diagram includes various components such as resistors (R312, R308, R310, R313), capacitors (C389, C390), and integrated circuits (U23, TPS3808G09DBVR). The schematic highlights connections between these components, with specific labels for DC_1V8, DC_3V3, and ground (GND). The diagram also includes measurement points (TP43, TP20, TP3) and annotations for components like MR, SENSE1, VDD, CT, RESET, CT, GND, and others. The diagram is part of a larger technical document, with titles, page contents, and additional details provided in the image. The diagram is a representation of electrical connections and component placements within the system reset logic circuitry.
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